



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-01-30
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	AMS/IPD Materials Declaration Champion)
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	A8V2*L095BA6	A	BO2A	2013-01-30
Amount	UoM	Unit type	ST ECOPACK Grade	
5600.00	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used	bright, annealed Tin/Silver/Bismuth	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	17.25X20.20X5	13	Through-hole	
Comment	PACKAGE: MULTIWATT 15L SPLIT VERT.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
JIG R	7a-Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList :REACH-19 December 2012				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	ABV2*L095BA6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	6.311	mg	supplier	die	Silicon (Si)	7440-21-3		6.085	mg	964190	1087
				supplier	metallization	Aluminium (Al)	7429-90-5		0.093	mg	14736	17
				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.026	mg	4120	5
						Silicon Oxide(SiO2)	7631-86-9		0.049	mg	7764	9
						Gamma-butyrolactone	96-48-0		0.035	mg	5546	6
						Polyhydroxyamide	55295-98-2		0.016	mg	2535	3
						Alcoxyilane	proprietary		0.001	mg	158	0
						Aryl Silicic Acid	proprietary		0.001	mg	158	0
				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	158	0
						Nickel (Ni)	7440-02-0		0.004	mg	634	1
Leadframe + Slug	Copper & its alloys	3048.723	mg	supplier	alloy	Copper (Cu)	7440-50-8		3039.938	mg	997118	542846
						Iron (Fe)	7439-89-6		1.4	mg	459	250
						Iron Phosphide (FeP)	26508-33-8		2.557	mg	839	457
				supplier	metallization	Silver (Ag)	7440-22-4		4.828	mg	1584	862
Soft solder	Other organic materials	4.799	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	4.679	mg	974995	836
				supplier	solder	Silver (Ag)	7440-22-4		0.072	mg	15003	13
						Tin (Sn)	7440-31-5		0.048	mg	10002	9
Bonding wire	Other inorganic materials	0.707	mg	supplier	wire	Copper (Cu)	7440-50-8		0.707	mg	1000000	126
						Silica vitreous	60676-86-0		1963.712	mg	780000	350663
encapsulation	Other organic materials	2517.58	mg	supplier	mold compound	Bisphenol F type epoxy resin	9003-36-5		239.17	mg	95000	42709
						Phenol resin	9003-35-4		226.582	mg	90000	40461
						Antimony Trioxide	1309-64-4		42.799	mg	17000	7643
				JIG I	mold compound	Brominated flame retardant	Proprietary		37.764	mg	15000	6744
				supplier	mold compound	Carbon Black	1333-86-4		7.553	mg	3000	1349
connections coating	Solder	21.88	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		21.88	mg	1000000	3907